



Alliance Memory Inc.
12815 NE 124th St., Suite D, Kirkland, WA 98034 USA
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Product Change Notification (PCN)

Date: 23 May 2025

PCN TRACKING NO: PDN#23052025

Subject: Product Change Notification (PCN) for Alliance Memory Part Number **ASFC8G31M-51BIN**
(8GB eMMCV5.1 rev0 part)

Affected Part Numbers	ASFC8G31M-51BIN & ASFC8G31M-51BINTR
Description of Change:	End-Of-Line of ASFC8G31M-51BIN / TR parts. Products will be offered in revision A
Reason for Change	MLC NAND Wafer FAB Line shutdown Products will be offered in revision A for better longevity
Traceability, Guidelines	Traceable through marketing orderable part numbers
Alternative Part	Refer to Table.1
Summary of Alternative	Alternative parts uses active MLC NAND Flash from 16nm process technology active supplier

Table. 1: Affected and Alternative Active Part Numbers

Product	Alliance EOL Part Numbers	Alliance Alternative Part Number
8GB eMMC-v5.1	ASFC8G31M-51BIN ASFC8G31M-51BINTR	ASFC8G31MA-51BIN ASFC8G31MA-51BINTR

Last Time Buy Date:	September 30 th , 2025
Last Time Ship Date:	March 31 st , 2026
Sample Availability Date for alternative part number	Now
PCN Effective Date	May 23 rd , 2025

Please contact your local sales representative if you have any questions regarding this PCN.



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Dear Valued Customer:

This letter provides End-of-Life (EOL) notice of products for Alliance Memory 8GB rev.0 eMMC v5.1 Industrial Temperature Grade part numbers ASFC8G31M-51BIN & ASFC8G31M-51BINTR. Alternatives to these products will continue to be offered as rev.A option in Industrial Temperature Grade.

The delivery deadline is **March 31st, 2026** with last time buy (LTB) deadline on **September 30th, 2025**. Please note that the standard shipment dates will apply in general and extended delivery dates must be pre-arranged and accepted in writing by Alliance Memory Management.

Alliance Memory Inc. will make all reasonable commercial efforts to honor all purchase orders placed before LTB and scheduled delivery dates but reserves the right to not accept new orders or to cancel existing orders if they cannot be fulfilled.

Samples for Alternative part numbers as listed in Table.1 are available for customers to order samples now to start verification or qualification procedures.

Please contact your local Alliance Memory representative if you have any questions regarding this PCN notification or write to us at quality@alliancememory.com

Yours faithfully


David Bagby
President
Alliance Memory Inc.





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ASFC8G31M-51BIN vs ASFC8G31MA-51BIN Comparison

Part Number & result Parameter	ASFC8G31M-51BIN	ASFC8G31MA-51BIN	Comparison Result
Product Description	eMMCv5.1 , Rev.0	eMMC v5.1, rev.A	
Capacity	8GB	8GB	Same
Bus Width	x1 (default), x4 & x8	x1 (default) , x4 & x8	Same
eMMC Version	v5.1 (backward compatible with previous MMC versions)	v5.1 (backward compatible with previous MMC versions)	Same
Operating Power Supply (Controller)	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	Same
Operating Power Supply (NAND)	Vcc = 2.7V~3.6V	Vcc = 2.7V~3.6V	Same
Operating Temperature	Industrial (Ta = -40°C ~ 85°C)	Industrial (Ta = -40°C ~ 85°C)	Same
Storage Temperature	-40°C ~ 85°C	-40°C ~ 85°C	Same
Clock Frequency	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	Same
Interface Timing Mode	HS200/ HS400	HS200/ HS400	Same
NAND Flash Component	Density: 64Gb Die:1, MLC	Density: 64Gb Die:1, MLC	Same
Enhance mode support Configure pSLC mode	No	Yes	Rev.A better
Boot Partition 1	4096KB	4096KB	Same
Boot Partition 2	4096KB	4096KB	Same
Boot Ack Time	<50 ms	<50ms	Same
Boot Data Time	<1 Sec	<1 Sec	Same
Sequential Performance (HS400)	Write: 80MB/s Read = 140MB/s	Write: 68MB/s Read = 278MB/s	Comparable
Active Power Consumption	VCCQ = 120mA VCC = 120mA	VCCQ = 175mA VCC = 129mA	Comparable
Standby Power Consumption	VCCQ = 600uA VCC = 50uA	VCCQ = 420uA VCC = 110uA	Comparable
Sleep Power Consumption	VCCQ = 600uA	VCCQ = 400uA	Comparable
Package Type	153-ball TFBGA	153-ball TFBGA	Same
Package Outer Dimensions	11.5 x 13 x 1.0mm	11.5 x 13 x 0.8mm	Comparable
Package Ball pitch/matrix	0.5mm pitch, 6.5mm x 6.5mm	0.5mm pitch, 6.5mm x 6.5mm	Same
Package Material	Pb and Halogen Free	Pb and Halogen Free	Same
Pin to Pin Compatible	Yes.		